

deposition of residues on the printed circuit board.

Claim 22: (Added) The intermediate of claim 21, wherein the buffer consists essentially of sodium bicarbonate, potassium bicarbonate or a combination thereof, and wherein the concentration of the buffer in the rinsing solution is between 10 ppm and 450 ppm.

Claim 23: (Added) The intermediate of claim 21, wherein the buffer comprises an amphoteric buffer.

Claim 24: (Added) The intermediate of claim 23, wherein the amphoteric buffer comprises Tris-(hydroxymethyl) aminomethane, N-2-Hydroxyethylpiperazine-N'-2-ethanesulfonic acid, or N-morpholino)-ethanesulfonic acid.

Claim 25: (Added) The intermediate of claim 21, wherein the residue comprises an etchant.

Claim 26: (Added) The intermediate of claim 21, wherein the residue comprises copper.

Claim 27: (Added) The intermediate of claim 21, wherein the residue comprises particulate material.

Claim 28: (Added) The intermediate of claim 21, wherein the electronic substrate comprises an electronic interconnect structure.

Claim 29: (Added) The intermediate of claim 21, wherein the electronic substrate comprises an integrated circuit.

Claim 30: (Added) The intermediate of claim 21, wherein the electronic substrate comprises a printed circuit board.

Claim 31: (Added) The intermediate of claim 21, wherein the pH of the low species buffered fluid is between 7-14.

Claim 32: (Added) The intermediate of claim 31, wherein the pH of the low species buffered fluid is between 7.5-9.0.

Claim 33: (Added) The intermediate of claim 21, wherein the concentration of the buffer is between 400 ppm and 500 ppm.

IN THE SPECIFICATION

Insert the following before "Field of the Invention":

This application is a divisional of allowed application Serial Number 09/452015, filed November 30, 1999.

REMARKS

No new matter was added by this preliminary amendment.

Please use 30-4900 DIV - 4010 as the docket number for this application.